

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE8736 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =30V,I_D =21A

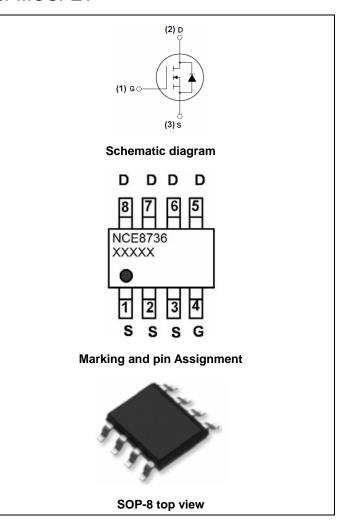
 $R_{DS(ON)} < 3.8 \text{m}\Omega @ V_{GS} = 10V$

 $R_{DS(ON)} < 5.5 \text{m}\Omega$ @ V_{GS} =4.5V

- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Package Marking and Ordering Information

	J	<u> </u>			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE8736	NCE8736	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	21	А
Drain Current-Continuous(T _A =100℃)	I _D (100℃)	14.9	Α
Pulsed Drain Current	I _{DM}	48	Α
Maximum Power Dissipation	P _D	3	W
Single pulse avalanche energy (Note 5)	E _{AS}	260	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	${\mathbb C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	42	°C/W
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Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V		-	±100	nA	
On Characteristics (Note 3)			•				
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.0	1.5	2.2	V	
Drain Course On State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =18A	-	2.8	3.8	mΩ	
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =18A	-	3.8	5.5		
Forward Transconductance	g FS	V _{DS} =5V,I _D =18A	50	-	-	S	
Dynamic Characteristics (Note4)			•				
Input Capacitance	C _{lss}	\/ 45\/\/ 0\/	-	2987	-	PF	
Output Capacitance	C _{oss}	V_{DS} =15V, V_{GS} =0V,	-	429	-	PF	
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	368	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	20	-	nS	
Turn-on Rise Time	t _r	V_{DD} =10 V , I_D =18 A	-	15	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =2.7 Ω	-	60	-	nS	
Turn-Off Fall Time	t _f		-	10	-	nS	
Total Gate Charge	Qg	V _{DS} =15V,I _D =18A,	-	70	-	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15V, I_D = 16A,$ $V_{GS} = 10V$	-	8.8	-	nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =1UV	-	16.3	-	nC	
Drain-Source Diode Characteristics	<u> </u>		•				
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =18A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	21	Α	

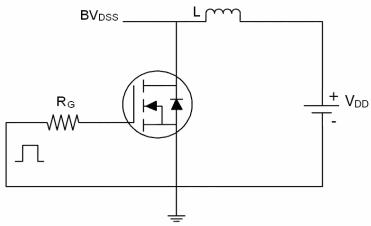
Notes:

- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^{\circ}\text{C}\,\text{,V}_\text{DD}\text{=}15\text{V}\text{,V}_\text{G}\text{=}10\text{V}\text{,L=}0.5\text{mH}\text{,Rg=}25\Omega$

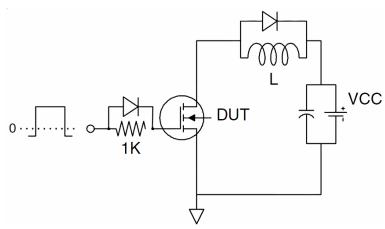


Test Circuit

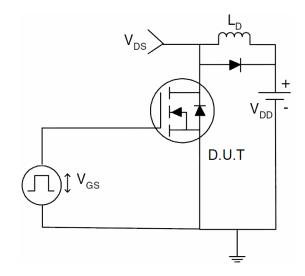
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

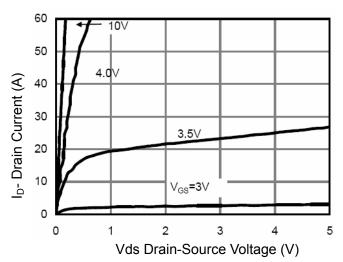


Figure 1 Output Characteristics

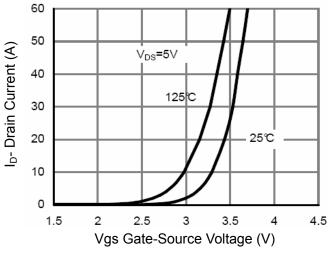


Figure 2 Transfer Characteristics

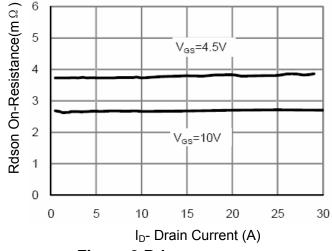


Figure 3 Rdson- Drain Current

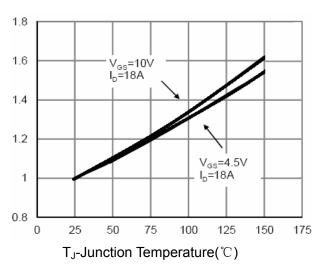


Figure 4 Rdson-JunctionTemperature

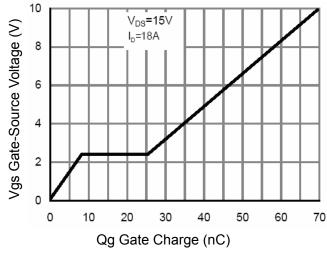


Figure 5 Gate Charge

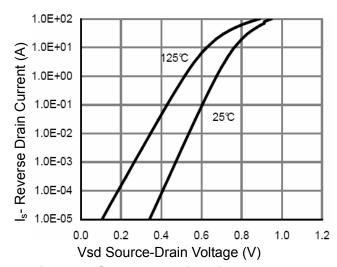


Figure 6 Source- Drain Diode Forward



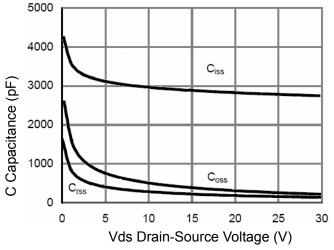


Figure 7 Capacitance vs Vds

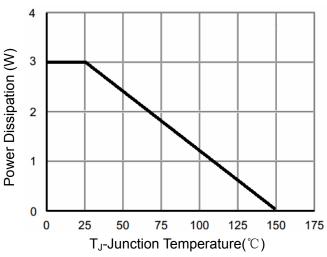


Figure 9 Power De-rating

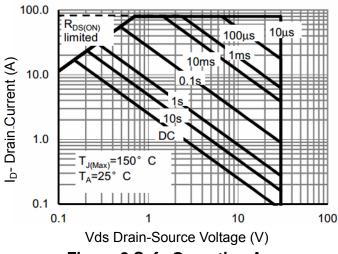


Figure 8 Safe Operation Area

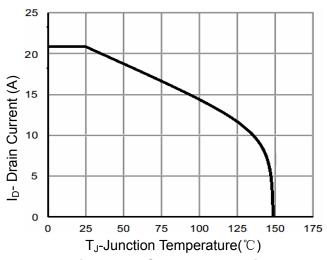
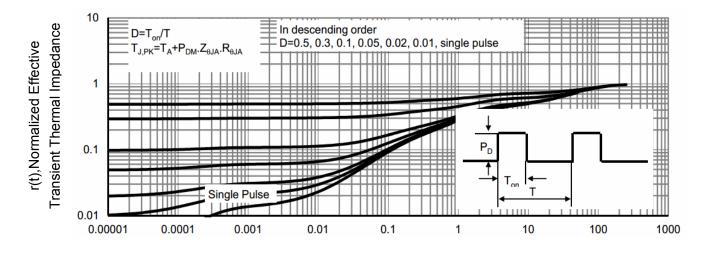


Figure 10 Current De-rating

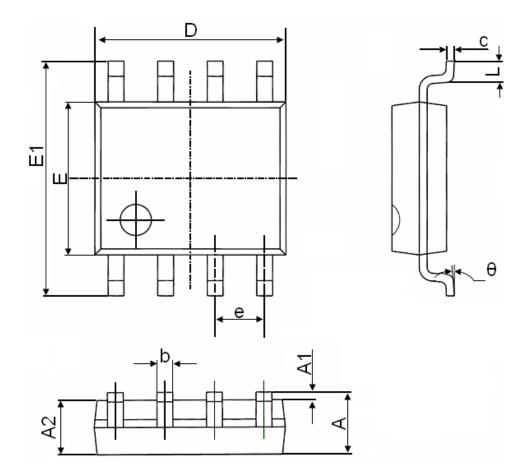


Square Wave Pluse Duration (sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	1.270(BSC)		(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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